

## CROWELL & MORING, L.L.P. P.O. Box 14300

Washington, D.C. 20044-4300 (202) 624-2500

November 21, 2001

## **Box PATENT APPLICATION**

Commissioner for Patents Washington, D.C. 20231

Re: New U.S. Patent Appln.

Our Ref: 381NP/50670

Sir:

Transmitted herewith for filing is the patent application of:

## Hiroyuki KADOTA

entitled:

ELECTROLYTIC GOLD PLATING METHOD AND APPARATUS

THEREFOR

Enclosed are:

- Specification, including 16 claims (pages 25, plus specification front page). 1.
- 4 Sheets of X Formal Informal drawings showing Figs. 1-5. 2.
- X Declaration and Power of Attorney (executed). 3.
- Assignment of the invention to Hitachi Kyowa Engineering Co., Ltd. 4.
- 5. The filing fee has been calculated as shown below:

Basic Fee							\$370/740	= \$740.00
Total Claims	30	_	20	= _	10	x	\$9/18	= \$180.00
Independent Claims	9	_	3	=	6	x	\$42/84	= \$504.00
Multiple Dependent Claim Presented						_	\$140/280	= \$280.00
Total Filing Fee								\$1,704.00

Two checks in the amount of  $\frac{1,704.00}{1}$  for the filing fee and  $\frac{40.00}{1}$  for the assignment recording fee are enclosed. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Deposit Account No. 05-1323 (Docket #381NP/50670). A duplicate copy of this sheet is enclosed.

Respectfully submitted,

rren A. Zitlau

Registration No. 39,085

James F. McKeown Registration No. 25,406

PATENT TRADEMARK OFFICE